

WEBENCH[®] Thermal Simulation Report

 Design : 4420283/1 LM3151MHX-3.3/NOPB
 LM3151MHX-3.3/NOPB 24.0V-32.0V to 3.30V @ 2.0A

Operating Condition

Name	Value
VIN_OP	32.0V
IOUT_OP	2.0A

Ambient Temperature

Name	Temperature
Ambient_plus_Z	30.0
Ambient_minus_Z	30.0



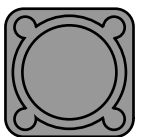


Air Flow


Name	Direction
Flow_Type	Convection
Flow_Rate	0.0LFM
Flow_Direction	Top to Bottom

Edge Temperature

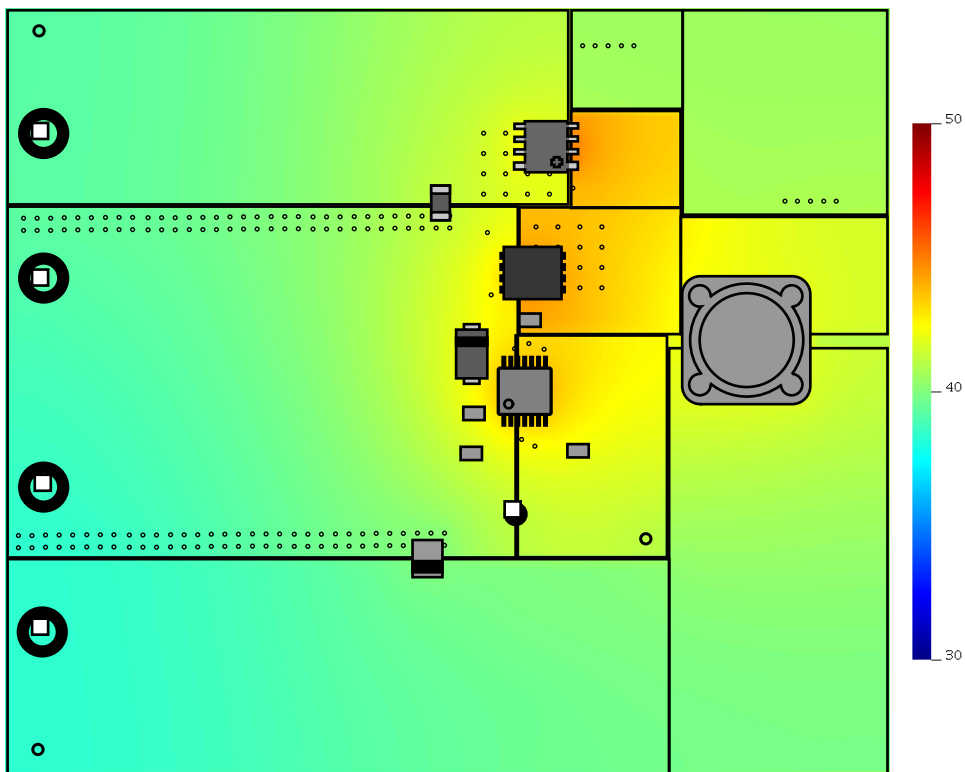
Name	Temperature	Thermal Type
Edge_plus_X (Right)		Insulated
Edge_minus_X (Left)		Insulated
Edge_plus_Y (Top)		Insulated
Edge_minus_Y (Bottom)		Insulated

BOM

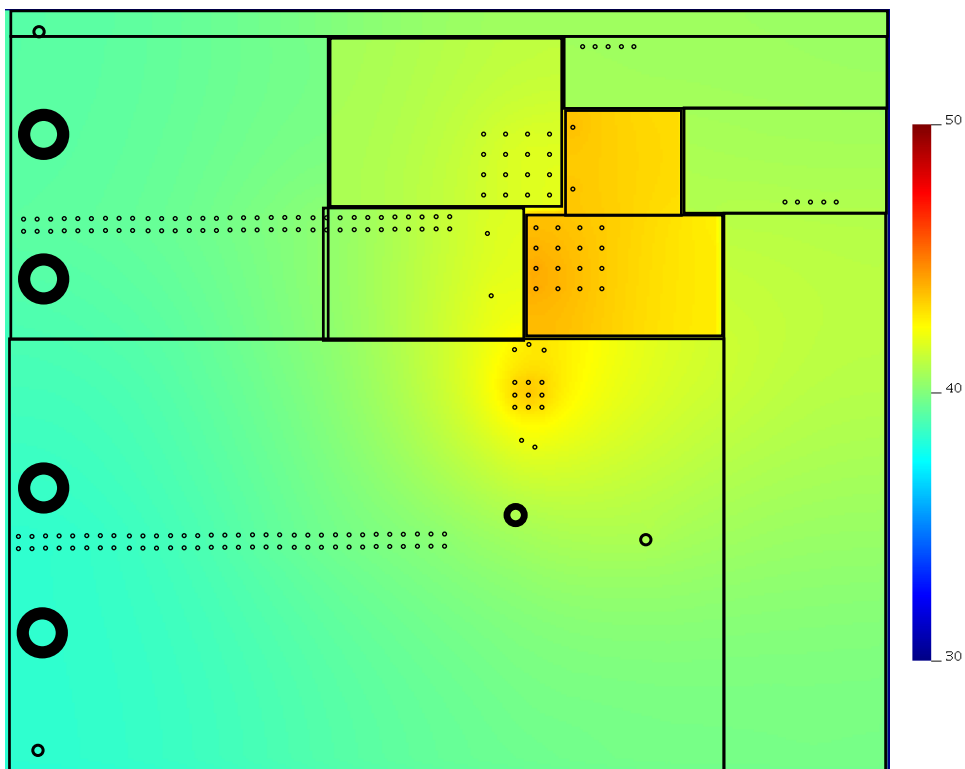
Component Name(s)	Part Number	Max Temp	Power Dissipation	Manufacture	Properties	Qty	Price	Footprint
pcb_bottom		44°C						
M1	SI4446DY	53°C	0.17W	Vishay-Siliconix	VdsMax=40.0V IdsMax=3.9Amps	1	\$0.28	 SOIC-8 55.131 mm ²
M2	BSC265N10LSF G	45°C	0.177W	Infineon Technologies	VdsMax=100.0V IdsMax=40.0Amps	1	\$0.52	 PG-TDSON-8 55.131 mm ²
L1	MSS1210-223MEB	42°C	0.13W	Coilcraft	L=2.2E-5H DCR=0.026Ohm	1	\$0.81	 MSS1210 204.49 mm ²
Cin	GRM31CR71H475KA12L	41°C	0.001W	MuRata	VDC=50.0V ESR=0.003Ohm IRMS=4.98A Cap=4.7E-6F	1	\$0.07	 1206 10.92 mm ²
Cout	6TPG100M	40°C	0.002W	Panasonic	VDC=6.3V ESR=0.07Ohm	1	\$0.39	

Component Name(s)	Part Number	Max Temp	Power Dissipation	Manufacture	Properties	Qty	Price	Footprint
					IRMS=1.0A Cap=1.0E-4F			3528-12 17.1 mm ²
U1	LM3151MHX-3.3/NOPB	46°C	0.371W	Texas Instruments		1	\$1.35	 MXA14A 58.8 mm ²
pcb_top		45°C						

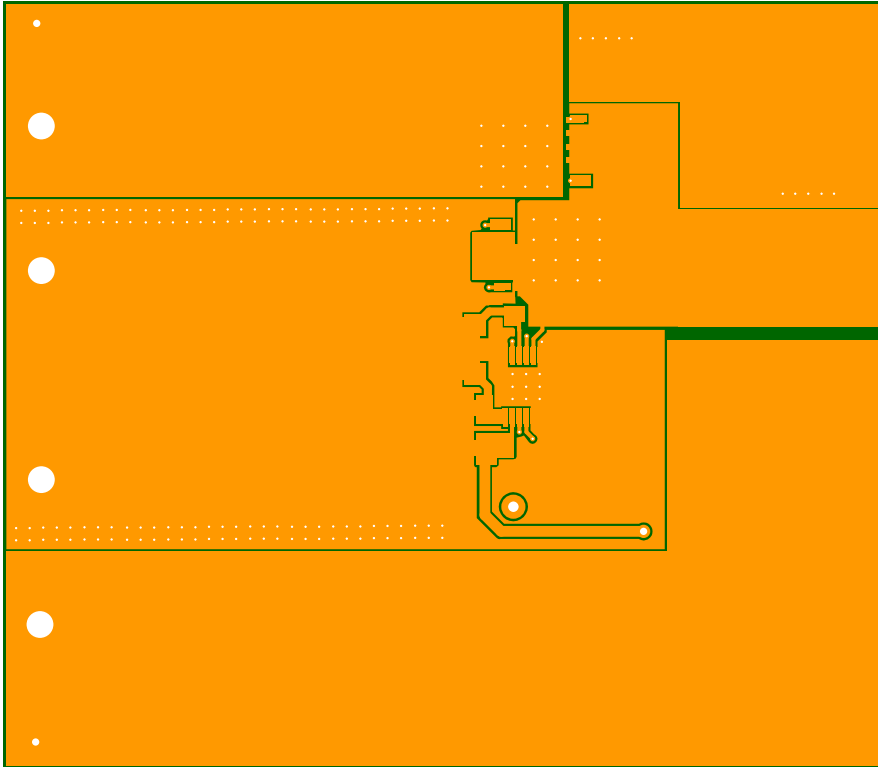
Thermal Images



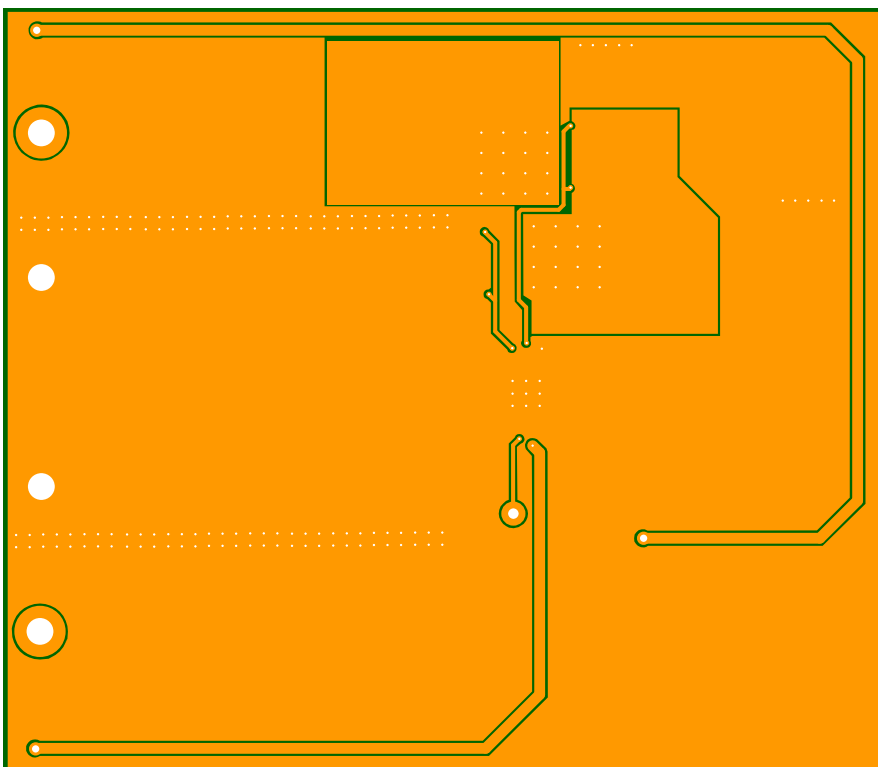
Thermal Top Image



Thermal Bottom Image

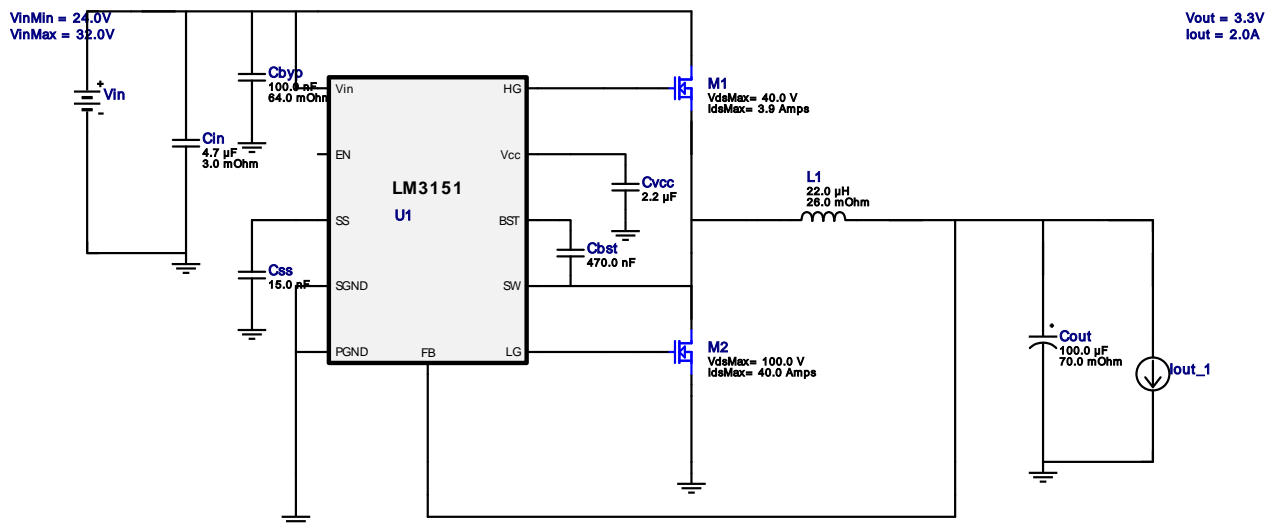


Top Image



Bottom Image

Schematic



Design Assistance

1. LM3151 Product Folder : <http://www.ti.com/product/LM3151> : contains the data sheet and other resources.

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